

REMARKS

Applicants respectfully request reconsideration of this application as amended. Claims 1 and 6 have been amended to present the claims in better form for allowance and for possible consideration on appeal. Applicants respectfully request the Examiner to accept the proposed amendments. Claims 14-39 have been previously cancelled. No new claims have been added. Therefore, claims 1-13 are now are presented for examination.

35 U.S.C. § 103 Rejection

Claim 1 stands rejected under 35 U.S.C. §103(a) as being unpatentable over Applicant's admitted prior art ("APA") in view of Yagi et al., U.S. Patent No. 6,109,507 ("Yagi").

Applicants submit that Yagi discloses "forming solder bumps on pads provided on a board, wherein a plurality of solder bump layer forming cycles are repeatedly implemented" (Abstract). Yagi further discloses that "the melting point of the solder particle is higher than the evaporation point of the flux. Thus . . . the solder particles will melt and join with the pad. Then, there will be no air existing at the surface of the pad. (col. 3, lines 23-31).

In contrast, claim 1, in pertinent part, recites "applying a no-clean flux to a first surface of a substrate . . . [and] bringing the solder bumps into contact with the corresponding metal bumps via a thermo-compression bonder." (emphasis provided). Applicants submit that neither APA nor Yagi, individually, or when combined, in any combination, teach or reasonably suggest applying a no-clean flux or via a thermo-

compression bonder, as recited by claim 1. Accordingly, Applicants respectfully request that the rejection of claim 1 and its dependent claims be withdrawn.

Claims 2 and 5 stand rejected under 35 U.S.C. §103(a) as being unpatentable over APA in view of Yagi further in view of Hur et al., U.S. Patent No. 6,013,572 (“Hur”).

Claim 6 stands rejected under 35 U.S.C. §103(a) as being unpatentable over APA in view of Yagi further in view of Arbib, European Patent No. EP 0077622 (“Arbib”).

Claims 3, 4 and 7-13 stand rejected under 35 U.S.C. §103(a) as being unpatentable over APA in view of Yagi further in view of Kimura et al., U.S. Patent No. 6,400,034 (“Kimura”).

Claims 2-13 depend from claim 1 and thus include all its limitations. Accordingly, Applicants respectfully request the withdrawal of the rejection of claims 2-13.

Conclusion

In light of the foregoing, reconsideration and allowance of the claims is hereby earnestly requested.

Invitation for a Telephone Interview

The Examiner is requested to call the undersigned at (303) 740-1980 if there remains any issue with allowance of the case.

Request for an Extension of Time

Applicants respectfully petition for an extension of time to respond to the outstanding Office Action pursuant to 37 C.F.R. § 1.136(a) should one be necessary. Please charge our Deposit Account No. 02-2666 to cover the necessary fee under 37 C.F.R. § 1.17(a) for such an extension.

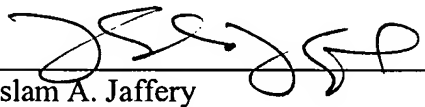
Charge our Deposit Account

Please charge any shortage to our Deposit Account No. 02-2666.

Respectfully submitted,

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Date: June 6, 2006



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